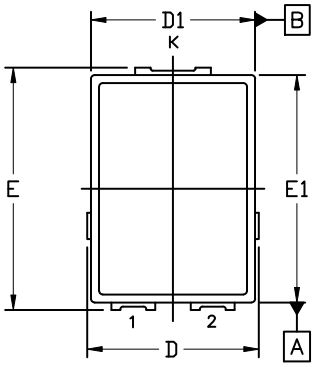
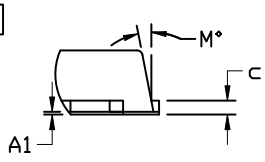
TO−277−3LD
CASE 340CZ
ISSUE A

DATE 14 FEB 2020

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS b, b1,b2,b3,b6 AND c TO BE MEASURED ON FLAT SECTION OF THE LEAD, BETWEEN 0.13 AND 0.25mm FROM LEAD TIP.
4. COPLANARITY APPLES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. POSITIONAL TOLERANCE APPLIES TO THE TERMINALS AND EXPOSED PAD.
6. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
7. DIMENSIONS D AND E TO BE DETERMINED AT DATUM PLANE C.



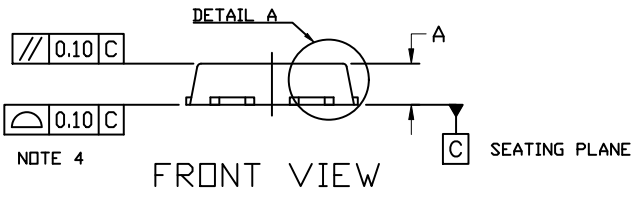
TOP VIEW



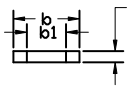
DETAIL A

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	1.00	1.10	1.20
A1	---	0.01	0.05
b	1.13	1.18	1.28
b1		0.70 REF	
b2	1.98	2.03	2.13
b3		1.20 REF	
b4		0.71 REF	
c		0.20 REF	
D	4.45	4.60	4.75
D1	4.35	4.40	4.45
D2	3.50	3.60	3.70

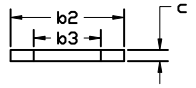
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
E	6.35	6.50	6.65
E1	6.05	6.10	6.15
E2	4.50	4.60	4.70
E3	3.84	3.94	4.04
E4		0.98 REF	
e		2.13 BSC	
K		0.85 REF	
K1		0.40 REF	
L	0.90	1.05	1.20
L1	0.02	---	---
M	---	---	12°



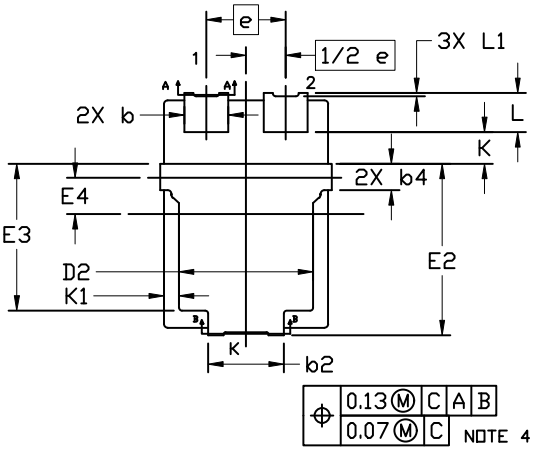
FRONT VIEW



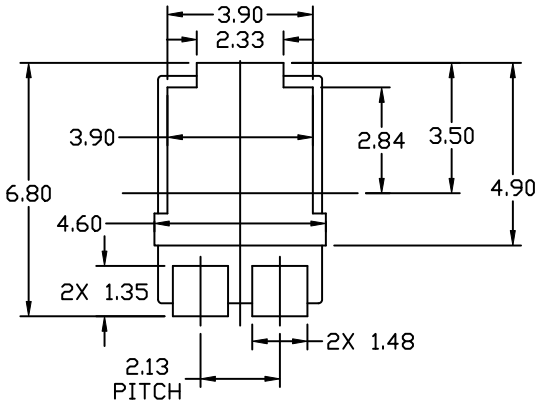
SECTION A−A



SECTION B−B



BOTTOM VIEW



RECOMMENDED
MOUNTING FOOTPRINT

* For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

XXXXXX = Specific Device Code
A = Assembly Location
Y = Year
W = Work Week
WL = Wafer Lot

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present. Some products may not follow the Generic Marking.

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